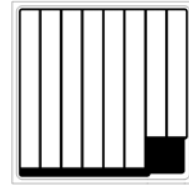


# High Efficiency 30 mil Infrared Thinfilm LED (850 nm) Lead (Pb) Free Product - RoHS Compliant

F3573C



**DRAFT - This design is for Reference only.  
Subject to change without notice.**

## Features

- High efficiency due to new Thinfilm concept
- Lambertian Emission pattern
- Polarity: n-side up
- Centroid wavelength (typ.): 850 nm
- Technology: AlGaAs Thinfilm

## Applications

- Infrared illumination for cameras
- Sensors

## Safety advice

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

**Here you can find important REACH information of OSRAM Opto Semiconductors' products:**

[http://www.osram-os.com/osram\\_os/EN/Products/REACH](http://www.osram-os.com/osram_os/EN/Products/REACH)

Please also note the special information in the section „Handling and storage conditions“ on page 6.

Type	Ordering Code	Description
F3573C	on request	30 mil high efficiency Thinfilm chip, 840 - 860 nm

**Electrical values**<sup>1)</sup> ( $T_A = 25\text{ °C}$ , correlated to TO18 package, bare die)

Parameter	Symbol	Value <sup>2)</sup>			Unit
		min.	typ.	max.	
Centroid wavelength $I_F = 500\text{ mA}$ , $t_p = 10\text{ ms}$	$\lambda_{\text{centroid}}$	840	850	860	nm
Forward voltage $I_F = 500\text{ mA}$ , $t_p = 10\text{ ms}$	$V_F$		1.6	2.0	V
Radiant power $I_F = 500\text{ mA}$ , $t_p = 10\text{ ms}$	$\Phi_e$	150			mW
Switching times, $\Phi_E$ from 10% to 90% and from 90% to 10%, $I_F = 500\text{ mA}$ , $R_L = 50\ \Omega$ .	$t_r / t_f$		11 / 15		ns
Temperature Coefficient of $\Phi_E$ <sup>3)</sup> $I_F = 500\text{ mA}$	$TC_I$		-0.3		%/K
Temperature Coefficient of $V_F$ <sup>3)</sup> $I_F = 500\text{ mA}$	$TC_V$		-1		mV/K
Temperature Coefficient of $\lambda$ <sup>3)</sup> $I_F = 500\text{ mA}$	$TC_\lambda$		0.3		nm/K

<sup>1)</sup> Measurement limits describe actual settings and do not include measurement uncertainties. Each wafer and fragment of a wafer is subject to final testing. The wafer or its pieces are individually attached on foils (rings). All el. values are referenced to the vendor's measurement system (correlation to customer product(s) is required). Measurement uncertainty +/-15% for brightness, +/- 1nm for wavelength and +/- 0.1V for voltage.

<sup>2)</sup> Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

<sup>3)</sup> The values given represent the chip in an OSRAM Opto Semiconductor's OSRON Compact package. Values may be different in other packages.

**Maximum Ratings<sup>1)</sup>**

Parameter	Symbol	Value	Unit
Maximum operating temperature range	$T_{op}$	-40...+100	°C
Maximum DC forward current ( $T_A = 25^\circ\text{C}$ )	$I_F$	500	mA
Minimum DC forward current ( $T_A = 25^\circ\text{C}$ )	$I_F$	50	mA
Maximum surge Current ( $T_A = 25^\circ\text{C}$ ) $t_p < 1 \text{ ms}, D = 0$	$I_{peak}$	1	A
Reverse current not designed for reverse operation	$I_R$		$\mu\text{A}$
Maximum junction temperature	$T_j$	125	°C

<sup>1)</sup> Maximum ratings are strongly package dependent and may differ between different packages. The values given represent the chip in an OSRAM Opto Semiconductor's OSOLON Compact package.

**Mechanical values**

Parameter	Symbol	Value <sup>1)</sup>			Unit
		min.	typ.	max.	
Length of chip edge (x-direction)	$L_x$	0.70	0.75	0.80	mm
Length of chip edge (y-direction)	$L_y$	0.70	0.75	0.80	mm
Diameter of the wafer	$D$		100		mm
Die height	$H$	130	150	170	$\mu\text{m}$
Diameter of bondpad	d	135	150	165	$\mu\text{m}$

**Additional information**

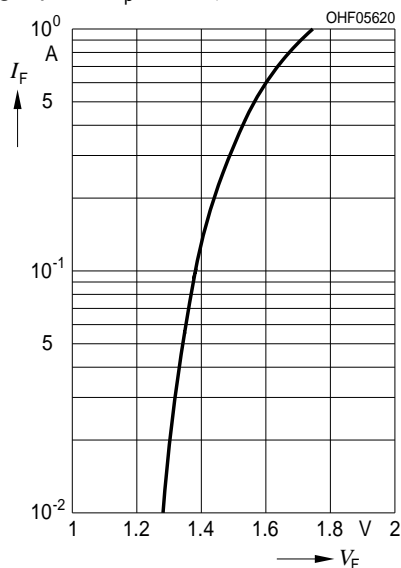
Metallization frontside	Gold
Metallization backside	Gold
Die bonding	Epoxy bonding

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**Forward current<sup>1)</sup>**

$I_F = f(V_F), T_A = 25\text{ °C}$

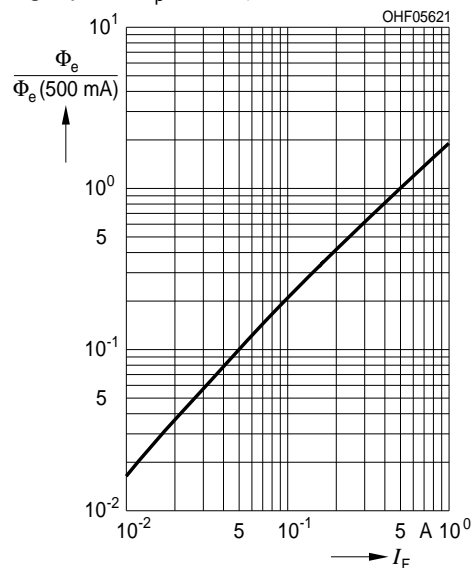
Single pulse,  $t_p = 100\text{ }\mu\text{s}$



**Relative total radiant flux<sup>1)</sup>**

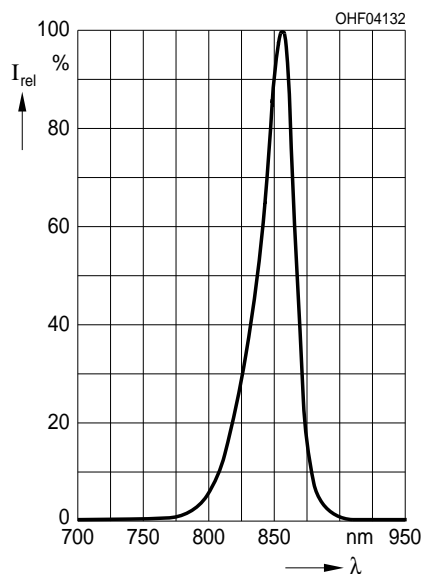
$\Phi_e / \Phi_e(500\text{mA}) = f(I_F), T_A = 25\text{ °C}$

Single pulse,  $t_p = 100\text{ }\mu\text{s}$



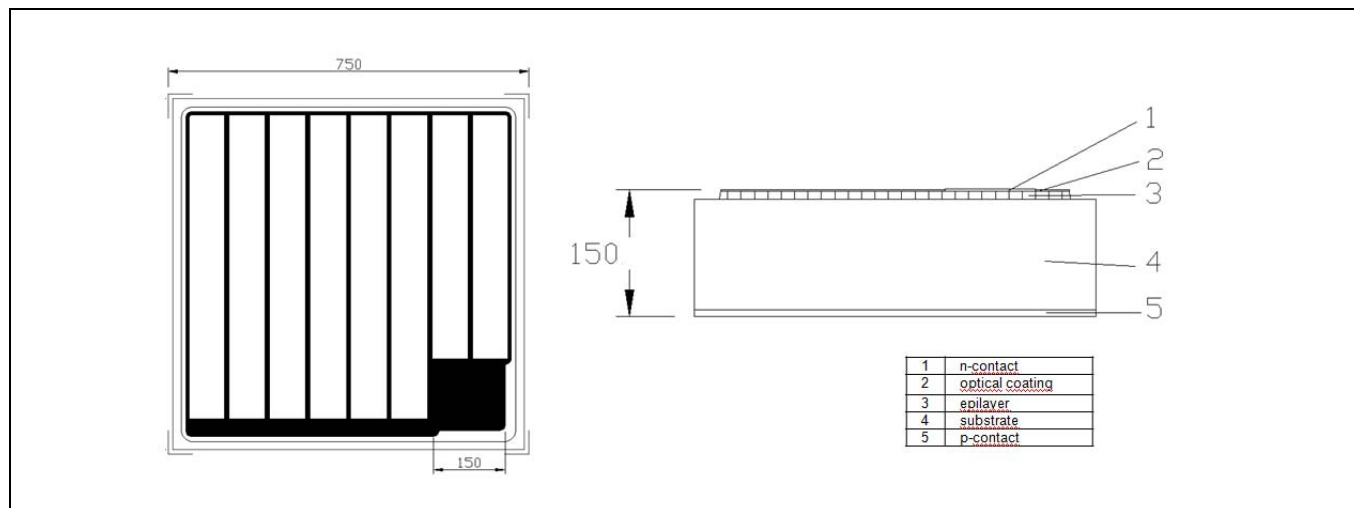
**Relative spectral emission<sup>1)</sup>**

$I_{rel} = f(\lambda), T_A = 25\text{ °C}$



<sup>1)</sup> Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice. Given values are package dependent.. The values represent the chip in an OSRAM Opto Semiconductor's OSOLON Compact package.

## Chip Outlines



Dimensions are specified as typical<sup>1)</sup> values as follows: μm

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### Attention please!

The information generally describes the type of component and shall not be considered as assured characteristics or detailed specification.

Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our sales organization.

### Handling and Storage Conditions:

Storage time for wafers in sealed condition shall not exceed 6 months (storage ambient conditions:  $T_a=15...30^{\circ}\text{C}$ ; relative humidity: < 60%). The hermetically sealed shipment lot shall be opened under temperature and moisture controlled cleanroom environment only. Customer has to follow the according rules for disposition of material that can be hazardous for humans and environment.

Chips are placed on a blue foil, which may contain the following substance in a concentration of circ.18% wt:

Bis (2-ethyl(hexyl)phthalate) (DEHP) [CAS #: 117-81-7; EC # 204-211-0].

Dice have to be handled ESD sensitive.

### Packing

Chips are placed on a blue foil, with a typical size of 18x18cm<sup>2</sup>.

For shipment the wafers of a shipment lot are arranged to stacks. The top and bottom of the stack is covered by a hard black cover to protect the top and bottom wafer from damage. The whole package sealed in a plastic bag for storage and shipment.

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You will have to bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### Label and shipping documents

Each wafer is identified with a sticker, which is attached to the back of each wafer. The label shows chip type, wafer number, quantity, binning and the minimum, average and maximum values of voltage, radiant power and wavelength. Each wafer shipment includes an additional document, which summarizes the content.

### Design objectives

a) workability

The chip design was developed and released based on the vendor's standard assembly procedures and packaging.

Bond strength properties are in accordance to MIL-STD-750D, method 2037. Whether the chip fits to the customer's product(s) with its according die and wire bond procedures and packaging must be evaluated by the customer himself. If workability problems arise after this release a mutually conducted problem solving procedure has to be set up, if the chips are suspected of contributing to the problems

b) chip characteristics

The chips are produced by the vendor with best effort, but on chip level a subset of the chip characteristics can be determined only. Performance of the chip in the customer's product(s) can only be determined by the customer himself.

### Returns/Complaints

To return material because of technical or logistical reasons a RMA-number is necessary. Samples for analysis purposes can be send to OSRAM OS without credit.

### Shipping Conditions:

If not otherwise arranged, the "General Conditions for the supply of products and services of the electrical and electronics industry" apply for any shipment. If these documents are not familiar to you, please request them at our nearest sales office.

### Components used in life-support devices or systems must be expressly authorized by us for such purpose!

Critical components<sup>2)</sup>, may only be used in life-support devices or systems<sup>3)</sup> with the express written approval of OSRAM OS.

### Disclaimer

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*<sup>1)</sup> Typical (referred to as typ.) data are defined as long-term production mean values and are only given for information. This is not a specified value.*

*<sup>2)</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.*

*<sup>3)</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.*

EU RoHS and China RoHS compliant product



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按照中国的相关法规和标准，不含有毒有害物质或元素。